SCLS304B - JANUARY 1996 - REVISED DECEMBER 2002

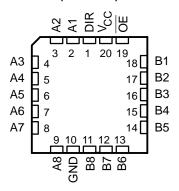
- Wide Operating Voltage Range of 2 V to 6 V
- **High-Current 3-State Outputs Can Drive Up** To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}

SN54HC645...J OR W PACKAGE SN74HC645 . . . DW, N, OR NS PACKAGE (TOP VIEW)

DIR [1	\bigcup_{20}] v _{cc}
A1 [2	19	OE
A2 [3	18	B1
A3 [4	17	B2
A4 [5	16] B3
A5 [6	15] B4
A6 [7	14] B5
A7 [8	13] B6
A8 [9	12] B7
GND [10	11] B8

- Typical $t_{pd} = 12 \text{ ns}$
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 µA Max
- **True Logic**

SN54HC645...FK PACKAGE (TOP VIEW)



description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending upon the level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so the buses are effectively isolated.

ORDERING INFORMATION

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube	SN74HC645N	SN74HC645N	
–40°C to 85°C	2010 PW	Tube	SN74HC645DW	110045	
	SOIC – DW	Tape and reel	SN74HC645DWR	HC645	
	SOP - NS	Tape and reel	SN74HC645NSR	HC645	
	CDIP – J	Tube	SNJ54HC645J	SNJ54HC645J	
–55°C to 125°C	CFP – W	Tube	SNJ54HC645W	SNJ54HC645W	
	LCCC – FK	Tube	SNJ54HC645FK	SNJ54HC645FK	

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

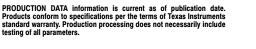
FUNCTION TABLE

INP	UTS	ODED ATION				
Œ	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	X	Isolation				

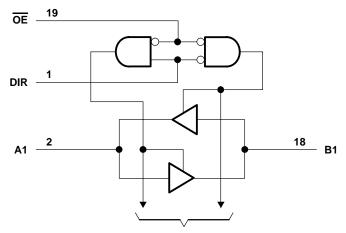


testing of all parameters.

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logic diagram (positive logic)



To Seven Other Transceivers

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see	Note 1) ±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2): DW p	ackage 58°C/W
N pac	kage 69°C/W
NS pa	ackage 60°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SI	N54HC64	15	SN	174HC64	5	UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII	
VCC	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V	
		V _{CC} = 6 V	4.2			4.2				
		V _{CC} = 2 V			0.5			0.5		
٧ _{IL}	Low-level input voltage	V _{CC} = 4.5 V			1.35			1.35	V	
		VCC = 6 V			1.8			1.8		
٧ı	Input voltage		0		VCC	0		VCC	V	
٧o	Output voltage		0		VCC	0		VCC	V	
		V _{CC} = 2 V			1000			1000		
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns	
		V _{CC} = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

SCLS304B - JANUARY 1996 - REVISED DECEMBER 2002

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

D4.0	AMETER	TEOT 00	NOTIONO	V	Т	A = 25°C	;	SN54H	IC645	SN74H	IC645	
PAR	AMETER	TEST CO	NDITIONS	v _{CC}	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
				2 V	1.9	1.998		1.9		1.9		
Voн		VI = VIH or VIL	$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
				6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
			$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
				2 V		0.002	0.1		0.1		0.1	
			$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1	
VOL		$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1		0.1		0.1	V
			I _{OL} = 6 mA 4.5 V 0.1		0.17	0.26		0.4		0.33		
			I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
II	DIR or OE	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	A or B	VO = VCC or 0		6 V		±0.01	±0.5		±10		±5	μΑ
ICC		$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci	DIR or OE			2 V to 6 V		3	10		10		10	pF

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то		T,	Վ = 25° C	;	SN54H	IC645	SN74H	C645	LINUT	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		40	105		160		130		
t _{pd}	A or B	B or A	4.5 V		15	21		32		26	ns	
			6 V		12	18		27		22		
			2 V		125	230		340		290		
t _{en}	ŌĒ	A or B	4.5 V		23	46		68		58	ns	
			6 V		20	39		58		49		
			2 V		74	200		300		250		
^t dis	ŌĒ	A or B	4.5 V		25	40		60		50	ns	
			6 V		21	34		51		43		
			2 V		20	60		90		75		
t _t		A or B	4.5 V		8	12		18	·	15	ns	
			6 V		6	10		15		13		

SN54HC645, **SN74HC645 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS**

SCLS304B - JANUARY 1996 - REVISED DECEMBER 2002

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

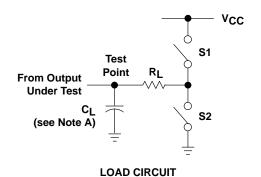
DADAMETED	FROM	то		T	√ = 25°C	;	SN54HC645		SN74HC645		UNIT	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
			2 V		54	135		200		170		
^t pd	A or B	B or A	4.5 V		18	27		40		34	ns	
·			6 V		15	23		34		29		
			2 V		150	270		405		335		
t _{en}	ŌĒ	A or B	4.5 V		31	54		81		67	ns	
			6 V		25	46		69		56		
			2 V		45	210		315		265		
t _t	t _t	A or B	4.5 V		17	42		63		53	ns	
			6 V		13	36		53		45		

operating characteristics, $T_A = 25^{\circ}C$

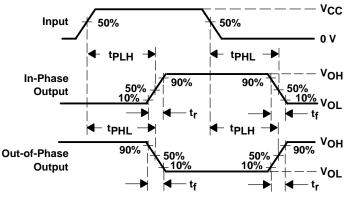
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver	No load	40	pF



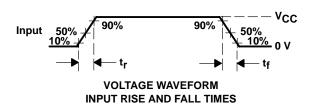
PARAMETER MEASUREMENT INFORMATION

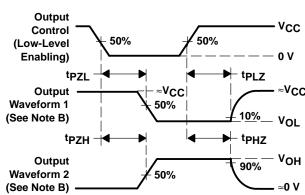


PARAI	METER	RL	CL	S1	S2	
	tPZH		50 pF or	Open	Closed	
t _{en}	tPZL	1 k Ω	150 pF	Closed	Open	
4	tPHZ	1 k Ω	50 pF	Open	Closed	
^t dis	tPLZ	1 K22	30 pr	Closed	Open	
t _{pd} or	t _{pd} or t _t		50 pF or 150 pF	Open	Open	



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES





VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN54HC645J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54HC645J	Samples
SN74HC645DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC645	Samples
SN74HC645N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC645N	Samples
SNJ54HC645FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HC 645FK	Samples
SNJ54HC645J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54HC645J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54HC645, SN74HC645:

Catalog: SN74HC645

Military: SN54HC645

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

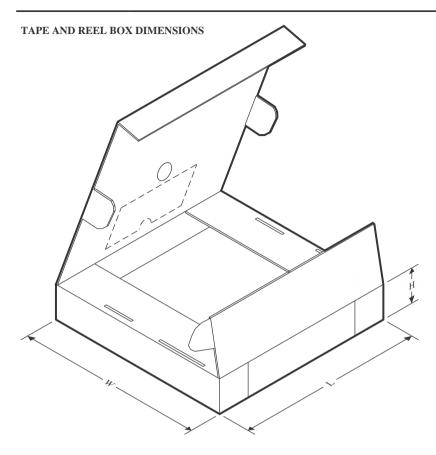


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC645DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device		Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
	SN74HC645DWR	SOIC	DW	20	2000	367.0	367.0	45.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HC645N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54HC645FK	FK	LCCC	20	55	506.98	12.06	2030	NA

14 LEADS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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